


Applicable standard					
Rating	Operating Temperature Range	-35 to +85°C (Note1)	Storage Temperature Range	-10 °C to +60°C (Note3)	
	Operating Humidity Range	20% to 80% (Note2)	Storage Humidity Range	40% to 70% (Note3)	
	Voltage	AC 150V (DC)	Applicable Connector	DF13-*S-1.25C	
	Current	1A/pin	Applicable crimp contact	DF13-2630SCF DF13G-2630SCF DF13-3032SCF	
<b>Specifications</b>					
Item		Test method		Requirements	QT AT
<b>Construction</b>					
General Examination		Visually and by measuring instrument.		According to drawing.	X X
Marking		Confirmed visually.			X X
<b>Electric Characteristics</b>					
Contact Resistance		100m A (DC or 1000 Hz).		30 mΩ MAX.	X —
Insulation Resistance		100 V DC.		500 MΩ MIN.	X —
Voltage Proof		500 V AC for 1 min.		No flashover or breakdown.	X —
<b>Mechanical Characteristics</b>					
Mechanical Operation		30 times insertion and extraction.		1.Contact resistance: 30 mΩ MAX. 2.No damage, crack or looseness of parts.	X —
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.		1.No electrical discontinuity of 1 μ s. 2.No damage, crack or looseness of parts.	X —
Shock		Acceleration 490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.			X —
<b>Environmental Characteristics</b>					
Damp Heat (Steady State)		Exposed at 40 ± 2°C , humidity 90 to 95 %, 96 h. (After leaving the room temperature for 1 to 2h.)		1.Contact resistance: 30 mΩ MAX. 2.Insulation resistance: 500 MΩ MIN. 3.No damage, crack or looseness of parts.	X —
Rapid Change Of Temperature		Temperature -55→ 5 to 35→85→ 5 to 35 °C Time 30→ 10 to 15 →30→ 10 to 15 min Under 5 cycles.		1.Contact resistance: 30 mΩ MAX. 2.Insulation resistance: 500 MΩ MIN. 3.No damage, crack or looseness of parts.	X —
Resistance to soldering heat		1) Solder bath method Soldered at solder temperature, 250 °C, for in immersion, duration, 10 sec. 2) Manual soldering Soldering iron temperature: 300 °C, Soldering time: 3 sec. No strength on contact.		1.Contact resistance: 40 mΩ MAX. 2.Insulation resistance: 100 MΩ MIN. 3.No damage, crack or looseness of parts.	X —
Solderability		Soldering temperature : 240°C Duration of immersion :soldering, for 3 sec.		1.Contact resistance: 40 mΩ MAX. 2.Insulation resistance: 100 MΩ MIN. 3.No damage, crack or looseness of parts.	X —
Remarks Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to packed condition.					
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
Unless otherwise specified, refer to IEC 60512.			APPROVED	S.J. OKAMURA	20211216
			CHECKED	SZ. ONO	20211216
			DESIGNED	TH. SATO	20211215
			DRAWN	TH. SATO	20211215
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-162420-25-00
	SPECIFICATION SHEET		PART NO.	DF13-*P-1. 25DS (25)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.		△ 1/1